

IGN400

High-Performance Rugged Computing, Evolved

IGN400 brings power, reliability, and connectivity to the edge.

onlogic.com/ign400



Built To Do More

IGN400 reaches a new peak of rugged computing with powerful 8-core i7 or Xeon processing.

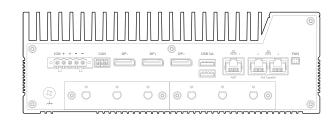
Designed For The Edge

Deployment is easy with IGN400, with deeply customizable DIO, integrated CAN bus, automotive power and flexible I/O configurations via ModBay™ expansion.

Engineered To Last

Rugged fanless design, wide operating temperature range, and leading shock and vibration resistance give IGN400 the durability for the toughest computing environments.





240 mm



System	
Processor	Support for Intel 8th & 9th Gen Processors Xeon E-2124G, E-2176G, E-2226GE, E-2278GE, E-2278GEL Core i7-8700, i7-8700T, i7-9700E, i7-9700TE Core i5-8500, i5-8500T, i5-9500E, i5-9500TE Core i3-8100, i3-8100T, i3-9100E, i3-9100TE Pentium 5400, 5400T Celeron 4900, 4900T
Processor Speed	1.8 ~ 3.7 GHz
Processor Cores	2~8
Chipset	Intel C246
Integrated Graphics	Intel UHD Graphics 610/630
Memory	2 DDR4 SO-DIMM slots 4 ~ 64 GB (ECC or non-ECC)

Rear I/O	
Ethernet	1 GbE LAN with Intel I219-LM controller 2 GbE LAN with Intel I210-AT controllers (PoE optional)
USB	2 USB 3.1 Gen 1
Video	3 DisplayPort
Power	5-Pin Terminal Block Power Input (9 ~ 48 V) Intelligent Ignition Sensing
Other	3-pin CAN bus 2 ModBay (4 LAN, 4 PoE, etc.) External Fan Connection

Front I/O		
USB	4 USB 3.1 Gen 1	
Serial	2 RS-232/422/485 COM	
Other	8-bit Isolated Digital I/O (4-in, 4-out) 2-pin Remote Power Switch 2 2.5" Hot-Swap Drives (optional) Audio jack (Line-In; Mic-In) External Mini-SIM slot Power button	

Expansion & Features		
Expansion & Storage	1 M.2 2280 M-key (PCle x4, SATA) 1 M.2 2230/60/80 M-key (PCle x2) 1 M.2 2230 E-key 2 mPCle (1 shared with mSATA) 2 SATA III 2.5" SSD/HDD (Optional Hot-swap)	
Onboard Connectors	2 ModBay for I/O Expansion	
Features	Onboard TPM 2.0	

Mechanical	
Dimensions (WxHxD)	240 x 82 x 242 mm (9.45 x 3.23 x 9.53 in)
Mounting Options	Wall-mount Wall-mount with Vibration Isolation

Environmental & Regulatory		
Operating Temperature	-40°C \sim 70°C with 35W TDP Processor -40°C \sim 50°C with 65W TDP Processor -40°C \sim 40°C with 80W TDP Processor	
Storage Temperature	-40°C ~ 85°C	
Shock	Tested according to IEC 60068-2-27 and MIL-STD-810G	
Vibration	Tested according to IEC 60068-2-64 and MIL-STD-810G	
Certifications	FCC 47 CFR Part 15 Low-Voltage (2014/35/EU) Electromagnetic Compatibility (2014/30/EU) Radio Equipment (2014/53/EU) - Only applicable for configurations with wireless transmitters EN 55032 EN 55035 ROHS 3 (2015/863/EU) WEEE Directive (2012/19/EU) Power Immunity According to E-Mark 7637-2 & 16750-2 EN 50121 Additional Safety and EMC certifications pending. Some certifications configuration dependent.	



IGN400 Dimensional Drawings

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All measurements in mm

